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1765

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Buie, et al.

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§ Group Art Unit: 1765

Serial No.: 10/024,958

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Examiner: Kin-Chan Chen

Confirmation No.: 3439

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Filed: December 18, 2001

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For: Etch Process Photolithographic
Reticle Manufacturing with
Improved Etch Bias

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MAIL STOP AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sirs:

CERTIFICATE OF MAILING

37 CFR 1.8

I hereby certify that this correspondence is being deposited on September 23, 2004 with the United States Postal Service as First Class Mail in an envelope addressed to: Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

September 23, 2004

Date

Signature

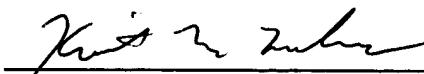
STATEMENT OF THE SUBSTANCE OF THE INTERVIEW

In response to the Interview Summary dated August 23, 2004, please enter Applicants' Statement of the Substance of the Interview.

An interview between Applicants and Examiner Chen was held on August 19, 2004. Applicants have no disagreement with the summary of the statements by the Examiner in the substance of the Examiner's Interview Summary dated August 23, 2004. Additionally, Applicants asserted in the August 19, 2004, interview, that there is no suggestion or motivation in the combined references of the method as recited by Applicants.

Agreement with respect to the claims was not reached.

Respectfully submitted,


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